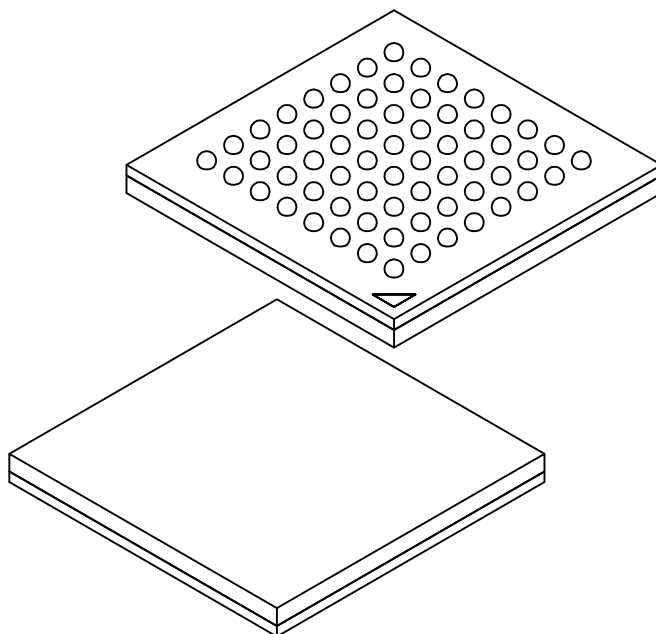


64-Ball Ultra Thin Fine-Pitch Ball Grid Array Package (BQB) - 5x5x0.65 mm Body [UFBGA]; Atmel Legacy Global Package Code CAH

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Terminals	N	64		
Pitch	e	0.50 BSC		
Overall Height	A	–	–	0.65
Ball Height	A1	0.14	0.19	0.24
Mold Thickness	M	0.25 REF		
Substrate Thickness	S	1.36 REF		
Overall Length	D	5.00 BSC		
Ball Array Length	D2	3.50 BSC		
Overall Width	E	5.00 BSC		
Ball Array Width	E2	3.50 BSC		
Ball Width	b	0.20	0.25	0.3

Notes:

- Pin 1 visual index feature may vary, but must be located within the hatched area.
- Dimensioning and tolerancing per ASME Y14.5M
 BSC: Basic Dimension. Theoretically exact value shown without tolerances.
 REF: Reference Dimension, usually without tolerance, for information purposes only.